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November 2013

# **FPF1038** Low On-Resistance, Slew-Rate-Controlled Load Switch

#### **Features**

- 1.2 V to 5.5 V Input Voltage Operating Range
- Typical Ron:
  - 20 m $\Omega$  at  $V_{IN}$ =5.5 V
  - 21 m $\Omega$  at  $V_{IN}$ =4.5 V
  - 37 m $\Omega$  at  $V_{IN}=1.8 \text{ V}$
  - 75 m $\Omega$  at  $V_{IN}=1.2 \text{ V}$
- Slew Rate / Inrush Control with t<sub>R</sub>: 2.7 ms (Typical)
- 3.5 A Maximum Continuous Current Capability
- Low <1 µA Shutdown Current
- ESD Protected: Above 8 kV HBM, 1.5 kV CDM
- GPIO / CMOS-Compatible Enable Circuitry

## **Applications**

- HDD, Storage, and Solid-State Memory Devices
- Portable Media Devices, UMPC, Tablets, MIDs
- Wireless LAN Cards and Modules
- **SLR Digital Cameras**
- Portable Medical Devices
- **GPS** and Navigation Equipment
- Industrial Handheld and Enterprise Equipment

## Description

The FPF1038 advanced load-management switch target applications requiring a highly integrated solution for disconnecting loads powered from DC power rail (<6 V) with stringent shutdown current targets and high load capacitances (up to 200 µF). The FPF1038 consists of slew-rate controlled low-impedance MOSFET switch (21 m $\Omega$  typical) and other integrated analog features. The slew-rate controlled turn-on characteristic prevents inrush current and the resulting excessive voltage droop on power rails.

These devices have exceptionally low shutdown current drain (<1 µA maximum) that facilitates compliance in low standby power applications. The input voltage range operates from 1.2 V to 5.5 V DC to support a wide range of applications in consumer, optical, medical, storage, portable, and industrial device power management.

Switch control is managed by a logic input (active HIGH) capable of interfacing directly with low-voltage control signal / GPIO with no external pull-up required. The device is packaged in advanced fully "green" 1mm x1.5 mm Wafer-Level Chip-Scale Packaging (WLCSP); providing excellent thermal conductivity, small footprint, and low electrical resistance for wider application usage.

## **Ordering Information**

Part Number	Top Mark	Switch R <sub>ON</sub> (Typical) at 4.5 V <sub>IN</sub>	Input Buffer	Output Discharge	ON Pin Activity	t <sub>R</sub>	Package
FPF1038UCX	QE	21 mΩ	CMOS	NA	Active HIGH	2.7 ms	6-Bump, WLCSP, 1.0 mm x 1.5 mm, 0.5 mm Pitch

## **Application Diagram**

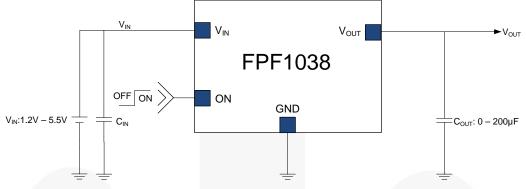


Figure 1. Typical Application

# **Functional Block Diagram**

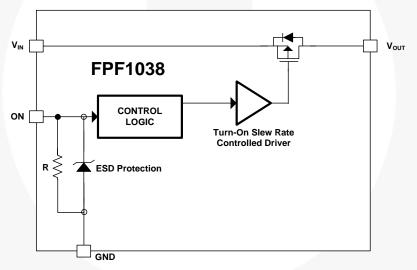


Figure 2. Functional Block Diagram

# **Pin Configuration**

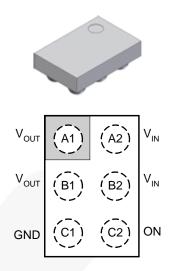


Figure 3. Top View

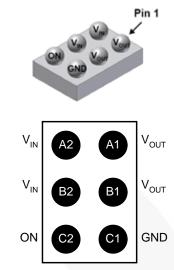


Figure 4. Bottom View

## **Pin Definitions**

Pin #	Name	Description
A1, B1	$V_{OUT}$	Switch Output
A2, B2	$V_{IN}$	Supply Input: Input to the Power Switch
C1	GND	Ground
C2	ON	ON/OFF Control, Active High - GPIO Compatible

## **Absolute Maximum Ratings**

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameters			Max.	Unit
V <sub>IN</sub>	V <sub>IN</sub> , V <sub>OUT</sub> , V <sub>ON</sub> to GND		-0.3	6.0	V
I <sub>SW</sub>	Maximum Continuous Switch Currer	nt		3.5	Α
P <sub>D</sub>	Power Dissipation at T <sub>A</sub> =25°C			1.2	W
T <sub>STG</sub>	Storage Junction Temperature		-65	+150	°C
T <sub>A</sub>	Operating Temperature Range		-40	+85	°C
	The man of Decistories It was time to Ame	hioma		85 <sup>(1)</sup>	°C/W
$\Theta_{JA}$	Thermal Resistance, Junction-to-Am	iblent		110 <sup>(2)</sup>	-C/VV
ESD	Electrostatic Discharge Canability	Human Body Model, JESD22-A114	8.0		kV
ESD	Electrostatic Discharge Capability	Charged Device Model, JESD22-C101	1.5		KV

#### Notes:

- Measured using 2S2P JEDEC std. PCB.
- 2. Measured using 2S2P JEDEC PCB COLD PLATE method.

## **Recommended Operating Conditions**

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to Absolute Maximum Ratings.

Symbol	Parameters	Min.	Max.	Unit
V <sub>IN</sub>	Input Voltage	1.2	5.5	٧
T <sub>A</sub>	Ambient Operating Temperature		+85	°C

## **Electrical Characteristics**

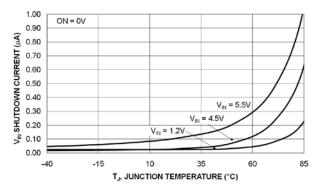
Unless otherwise noted, V<sub>IN</sub>=1.2 to 5.5 V and T<sub>A</sub>=-40 to +85°C; typical values are at V<sub>IN</sub>=4.5 V and T<sub>A</sub>=25°C.

Symbol	Parameters	Conditions	Min.	Тур.	Max.	Units	
Basic Oper	ation		1	I.	ı		
V <sub>IN</sub>	Input Voltage		1.2		5.5	V	
I <sub>Q(OFF)</sub>	Off Supply Current	V <sub>ON</sub> =GND, V <sub>OUT</sub> =Open			1.0	μA	
I <sub>SD</sub>	Shutdown Current	V <sub>ON</sub> =GND, V <sub>OUT</sub> =GND		0.2	1.0	μA	
IQ	Quiescent Current	I <sub>OUT</sub> =0 mA		5.5	8.0	μA	
		V <sub>IN</sub> =5.5 V, I <sub>OUT</sub> =1 A <sup>(3)</sup>		20	24		
		V <sub>IN</sub> =4.5 V, I <sub>OUT</sub> =1 A, T <sub>A</sub> =25°C		21	25	mΩ	
Б	On Resistance	V <sub>IN</sub> =3.3 V, I <sub>OUT</sub> =500 mA <sup>(3)</sup>		24	29		
$R_{ON}$		V <sub>IN</sub> =2.5 V, I <sub>OUT</sub> =500 mA <sup>(3)</sup>		28	35		
		V <sub>IN</sub> =1.8 V, I <sub>OUT</sub> =250 mA <sup>(3)</sup>		37	45		
		V <sub>IN</sub> =1.2 V, I <sub>OUT</sub> =250 mA, T <sub>A</sub> =25°C		75	100	1	
V <sub>IH</sub>	On Input Logic HIGH Voltage		1.0			V	
V <sub>IL</sub>	On Input Logic LOW Voltage				0.4	V	
I <sub>ON</sub>	On Input Leakage				1.0	μA	
Dynamic C	haracteristics			<u> </u>			
t <sub>DON</sub>	Turn-On Delay <sup>(4)</sup>			1.7		ms	
t <sub>R</sub>	V <sub>OUT</sub> Rise Time <sup>(4)</sup>	$V_{IN}=4.5 \text{ V}, \text{ R}_{L}=5 \Omega, \text{ C}_{L}=100 \mu\text{F}, \\ T_{A}=25^{\circ}\text{C}$		2.7		ms	
t <sub>ON</sub>	Turn-On Time <sup>(6)</sup>	1A-23 0		4.4		ms	
t <sub>DOFF</sub>	Turn-Off Delay <sup>(4)</sup>			2.0		ms	
t <sub>F</sub>	V <sub>OUT</sub> Fall Time <sup>(4)</sup>	$V_{IN}$ =4.5 V, R <sub>L</sub> =150 $\Omega$ , C <sub>L</sub> =100 $\mu$ F, T <sub>A</sub> =25°C, No Load Discharge		30.0		ms	
t <sub>OFF</sub>	Turn-Off <sup>(7)</sup>	TA-20 C, NO LOCK Discharge		32.0		ms	

#### Notes:

- 3. This parameter is guaranteed by design and characterization; not production tested.
- 4. t<sub>DON</sub>/t<sub>DOFF</sub>/t<sub>R</sub>/t<sub>F</sub> are defined in Figure 27.
- 5. Output discharge enabled during off-state.
- 6.  $t_{ON}=t_R + t_{DON}$
- 7.  $t_{OFF}=t_F + t_{DOFF}$

## **Typical Characteristics**



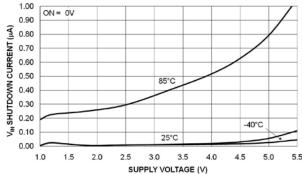
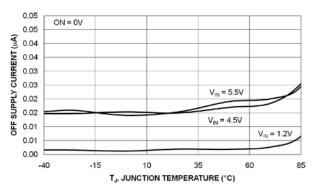


Figure 5. Shutdown Current vs. Temperature

Figure 6. Shutdown Current vs. Supply Voltage



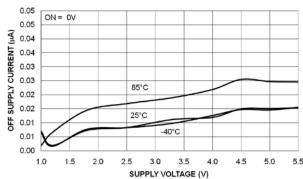
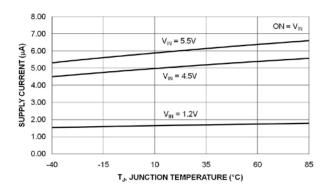


Figure 7. Off Supply Current vs. Temperature (V<sub>OUT</sub> Floating)

Figure 8. Off Supply Current vs. Supply Voltage  $(V_{\text{OUT}} \text{ Floating})$ 



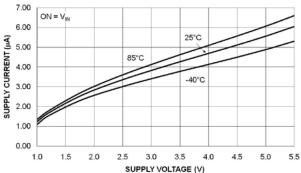
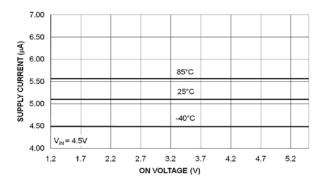


Figure 9. Quiescent Current vs. Temperature

Figure 10. Quiescent Current vs. Supply Voltage

## Typical Characteristics (Continued)



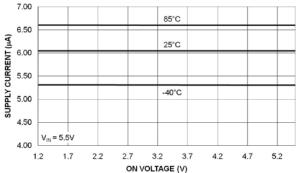
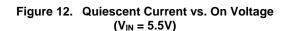
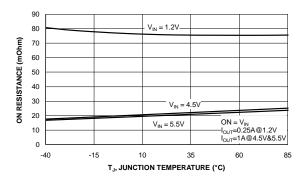


Figure 11. Quiescent Current vs. On Voltage (V<sub>IN</sub> = 4.5V)





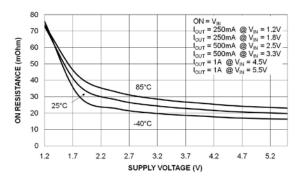
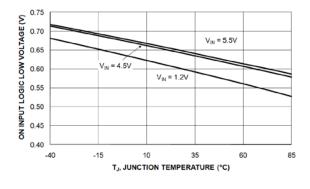


Figure 13. Ron vs. Temperature

Figure 14.  $R_{ON}$  vs. Supply Voltage



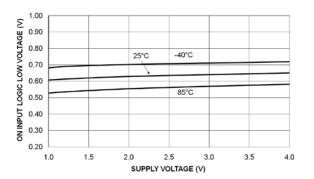


Figure 15. On Pin Threshold Low vs. Temperature

Figure 16. On Pin Threshold Low vs. VIN

## Typical Characteristics (Continued)

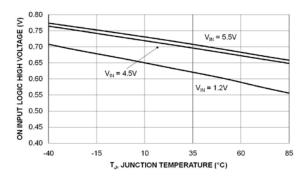


Figure 17. On Pin Threshold High vs. Temperature

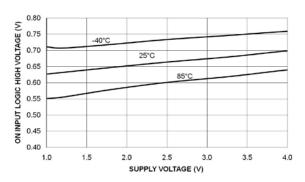


Figure 18. On Pin Threshold High vs. VIN

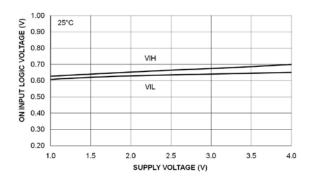


Figure 19. On Pin Threshold vs. Supply Voltage

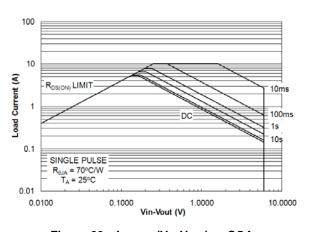


Figure 20. I<sub>SW</sub> vs. (V<sub>IN</sub>-V<sub>OUT</sub>) — SOA

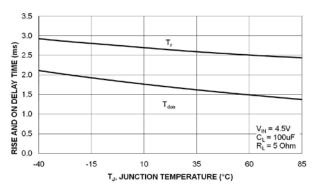


Figure 21. t<sub>R</sub>/t<sub>DON</sub> vs. Temperature

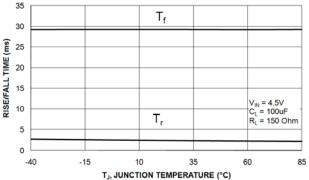
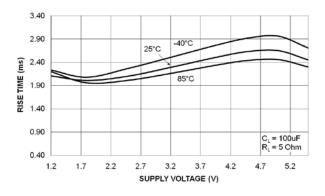


Figure 22.  $t_R/t_F$  vs. Temperature

## Typical Characteristics (Continued)



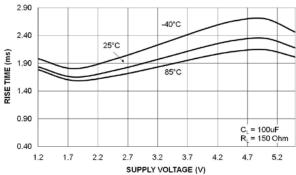
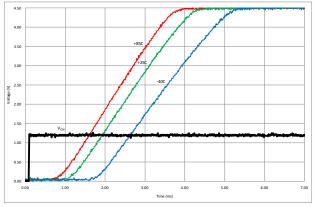


Figure 23. t<sub>R</sub> vs. Supply Voltage

Figure 24. t<sub>R</sub> vs. Supply Voltage



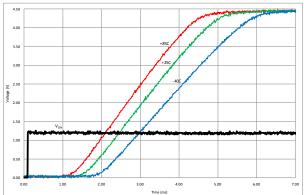


Figure 25. Turn-On Response (V<sub>IN</sub>=4.5 V, C<sub>IN</sub>=10  $\mu$ F, Figure 26. Turn-On Response (V<sub>IN</sub>=4.5 V, C<sub>IN</sub>=10  $\mu$ F, C<sub>L</sub>=100  $\mu$ F, R<sub>L</sub>=5  $\Omega$ )

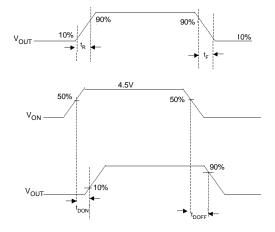


Figure 27. Timing Diagram

## **Application Information**

#### **Input Capacitor**

This IntelliMAX<sup>TM</sup> switch doesn't require an input capacitor. To reduce device inrush current, a 0.1  $\mu$ F ceramic capacitor,  $C_{IN}$ , is recommended close to the VIN pin. A higher value of  $C_{IN}$  can be used to reduce the voltage drop experienced as the switch is turned on into a large capacitive load.

## **Output Capacitor**

While this switch works without an output capacitor: if parasitic board inductance forces  $V_{OUT}$  below GND when switching off; a 0.1  $\mu F$  capacitor,  $C_{OUT}$ , should be placed between  $V_{OUT}$  and GND.

#### **Fall Time**

Device output fall time can be calculated based on RC constant of the external components as follows:

$$t_{\mathsf{F}} = \mathsf{R}_{\mathsf{L}} \times \mathsf{C}_{\mathsf{L}} \times 2.2 \tag{1}$$

where  $t_F$  is 90% to 10% fall time,  $R_L$  is output load, and  $C_L$  is output capacitor.

The same equation works for a device with a pull-down output resistor.  $R_L$  is replaced by a parallel connected pull-down and an external output resistor combination as:

$$t_{F} = \frac{R_{L} \times R_{PD}}{R_{L} + R_{PD}} \times C_{L} \times 2.2 \tag{2}$$

where  $t_F$  is 90% to 10% fall time,  $R_L$  is output load,  $R_{PD}\!\!=\!\!65~\Omega$  is output pull-down resistor, and  $C_L$  is the output capacitor.

#### Resistive Output Load

If resistive output load is missing, the IntelliMAX switch without a pull-down output resistor does not discharge the output voltage. Output voltage drop depends, in that case, mainly on external device leaks.

#### **Application Specifics**

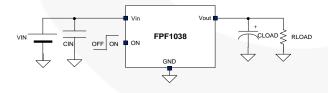


Figure 28. Device Setup

At maximum operational voltage ( $V_{IN}$ =5.5 V), device inrush current might be higher than expected. Spike current should be taken into account if  $V_{IN}$ >5 V and the output capacitor is much larger than the input capacitor. Input current can be calculated as:

$$I_{IN}(t) \approx \frac{V_{OUT}(t)}{R_{LOAD}} + (C_{LOAD} - C_{IN}) \frac{dV_{OUT}(t)}{dt} \tag{3}$$

where switch and wire resistances are neglected and capacitors are assumed ideal.

Estimating  $V_{OUT}(t)=V_{IN}/10$  and using experimental formula for slew rate  $(dV_{OUT}(t)/dt)$ , spike current can be written as:

$$max(I_{IN}) = \frac{V_{IN}}{10R_{LOAD}} + (C_{LOAD} - C_{IN})(0.05V_{IN} - 0.255)$$
(4)

where supply voltage  $V_{\text{IN}}$  is in volts, capacitances are in micro farads, and resistance is in ohms.

Example: If  $V_{IN}$ =5.5 V,  $C_{LOAD}$ =100  $\mu$ F,  $C_{IN}$ =10  $\mu$ F, and  $R_{LOAD}$ =50  $\Omega$ ; calculate the spike current by:

$$max(I_{1N}) = \frac{5.5}{10^*50} + (100 - 10)(0.05^*5.5 - 0.255)A = 1.8A$$
 (5)

Maximum spike current is 1.8 A, while average rampup current is:

$$I_{IN}(t) \approx \frac{V_{OUT}(t)}{R_{LOAD}} + (C_{LOAD} - C_{IN}) \frac{dV_{IN}(t)}{dt}$$
 (6)

 $\approx 2.75/50 + 100^*0.0022 = 0.275A$ 

## **Recommended Layout**

For best thermal performance and minimal inductance and parasitic effects, it is recommended to keep input and output traces short and capacitors as close to the device as possible. Figure 29 is a recommended layout for this device to achieve optimum performance.

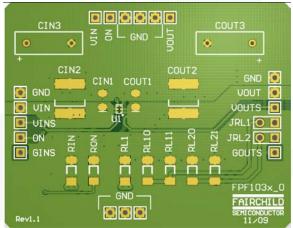


Figure 29. Recommended Land Pattern, Layout

## **Physical Dimensions**

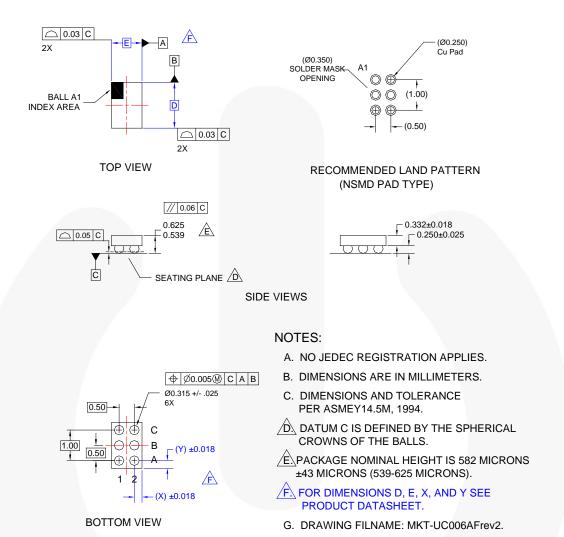


Figure 30. 6 Ball, 1.0 x 1.5 mm Wafer-Level Chip-Scale Packaging (WLCSP)

#### **Nominal Values**

Bump Overall Package		Silicon	Solder Bump	Solder Bump	
Pitch Height		Thickness	Height	Diameter	
0.5 mm 0.582 mm		0.332 mm	0.250 mm		

#### **Product-Specific Dimensions**

Product	D	E	X	Y
FPF1038UCX	1.5 mm ±0.03	1.0 mm ±0.03	0.240 mm	0.240 mm

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Counterfeiting of semiconductor parts is a growing problem in the industry. All manufacturers of semiconductor products are experiencing counterfeiting of their parts. Customers who inadvertently purchase counterfeit parts experience many problems such as loss of brand reputation, substandard performance, failed applications, and increased cost of production and manufacturing delays. Fairchild is taking strong measures to protect ourselves and our customers from the proliferation of counterfeit parts. Fairchild strongly encourages customers to purchase Fairchild parts either directly from Fairchild or from Authorized Fairchild Distributors who are listed by country on our web page cited above. Products outsomers buy either from Fairchild directly or from Authorized Fairchild Distributors are genuine parts, have full traceability, meet Fairchild's quality standards for handling and storage and provide access to Fairchild's full range of up-to-date technical and product information. Fairchild and our Authorized Distributors will stand behind all warranties and will appropriately address any warranty issues that may arise. Fairchild will not provide any warranty coverage or other assistance for parts bought from Unauthorized Sources. Fairchild is committed to combat this global problem and encourage our customers to do their part in stopping this practice by buying direct or from authorized distributors

#### PRODUCT STATUS DEFINITIONS

#### Definition of Terms

Datasheet Identification	Product Status	Definition
Advance Information	Formative / In Design	Datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary	First Production	Datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.
No Identification Needed	Full Production	Datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.
Obsolete	Not In Production	Datasheet contains specifications on a product that is discontinued by Fairchild Semiconductor. The datasheet is for reference information only.

Rev. 166

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